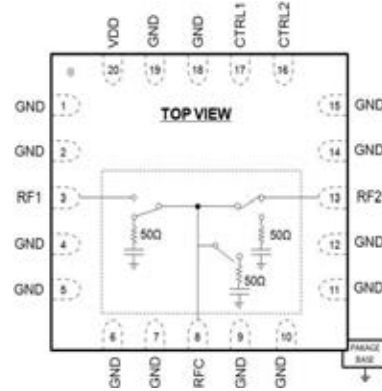




主要特点

工作频段: 0.1~ 6GHz
 插损: 0.8 dB
 隔离度: 60 dB
 P-0.1: 35 dBm
 IIP3: 58 dBm
 耐功率: +35 dBm (公共端), +29 dBm (负载端)
 I/O 控制电平: 兼容 1.8V/2.5V/3.3V LVTTTL, 5V TTL
 ESD: RF 2000V HBM, I/O 4000V HBM
 封装: 16-Lead, 4mmx4mm QFN

功能框图

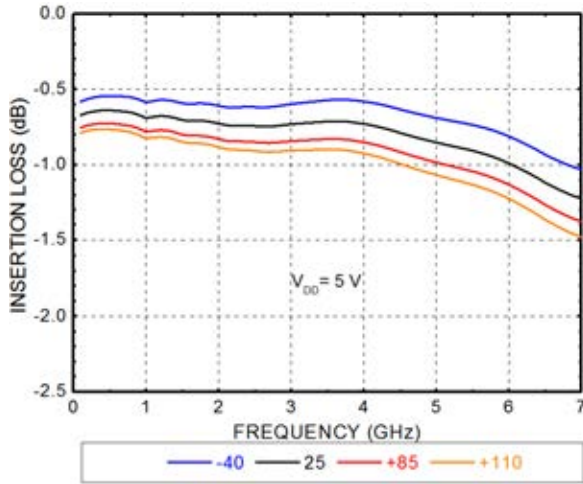


性能指标 ($T_A = +25^\circ\text{C}$, $V_{DD}=2.5\text{V}\sim 5\text{V}$, $V_{CTL}=0\text{V}/V_{DD}$, 50Ω)

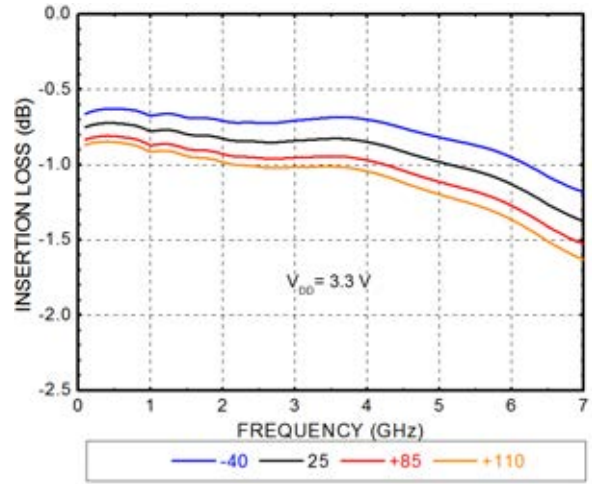
参数	条件		最小	典型	最大	单位
插损	0.1GHz~2GHz			0.6	1	dB
	2.0GHz~4.0GHz			0.7	1.1	dB
	4.0GHz~6.0GHz			0.9	1.3	dB
隔离	RFC~ RF1/RF2	0.1GHz~2GHz	50	60		dB
		2.0GHz~4.0GHz	45	50		dB
		4.0GHz~6.0GHz	40	45		dB
回波损耗	开态	0.1GHz~2GHz		25		dB
		2.0GHz~4.0GHz		25		dB
		4.0GHz~6.0GHz		15		dB
	关态	0.1GHz~2GHz		20		dB
		2.0GHz~4.0GHz		20		dB
		4.0GHz~6.0GHz		15		dB
开关时间	t_{RISE}, t_{FALL}	10%/90% RF_{OUT}		80		ns
	t_{ON}, t_{OFF}	50% V_{CTL} to 10%/90% RF_{OUT}		150		ns
输入功率压缩点	P-0.1	$V_{DD}=3.3\text{V}$		33		dBm
		$V_{DD}=5\text{V}$		35		dBm
	P-1	$V_{DD}=3.3\text{V}$		34		dBm
		$V_{DD}=5\text{V}$		36		dBm
IIP3	$P_{OUT}=12\text{dBm/tone}$, $f_{spacing}=1\text{MHz}$			58		dBm
工作电压	V_{DD}		2.5		5.5	V
控制电压	V_{CTL}, EN		0		V_{DD}	V
控制电压输入电平范围	$V_{DD}=+5.0\text{V}$	低电平 (V_{IL})	0		1.2	V
		高电平 (V_{IH})	1.6		5	V
	$V_{DD}=+3.0\text{V}$	低电平 (V_{IL})	0		0.8	V
		高电平 (V_{IH})	1.2		3.0	V
功耗	$V_{DD}=+5.0\text{V}$			110		μA
	$V_{DD}=+3.0\text{V}$			70		μA



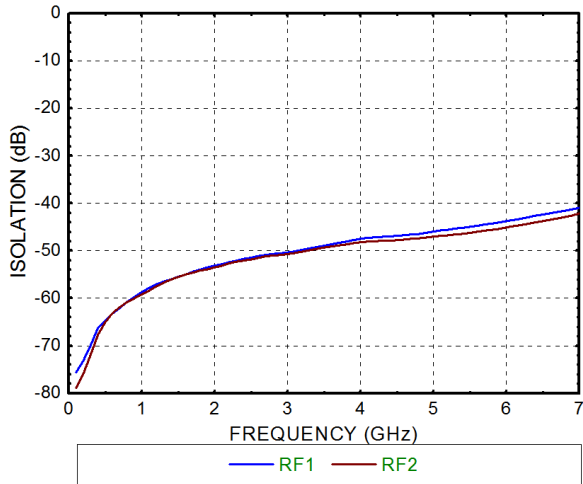
插损 vs. 温度



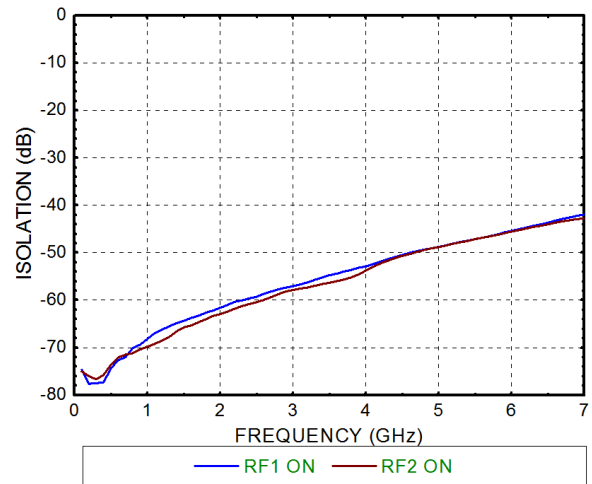
插损 vs. 温度



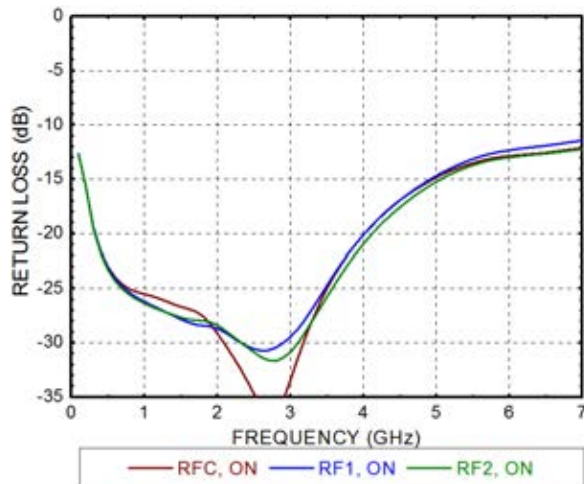
隔离度 (RFC~RF1/RF2)



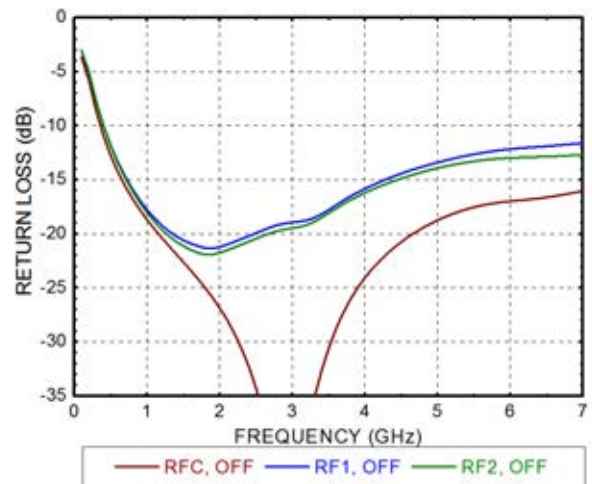
隔离度 (RF1~RF2)



回波损耗

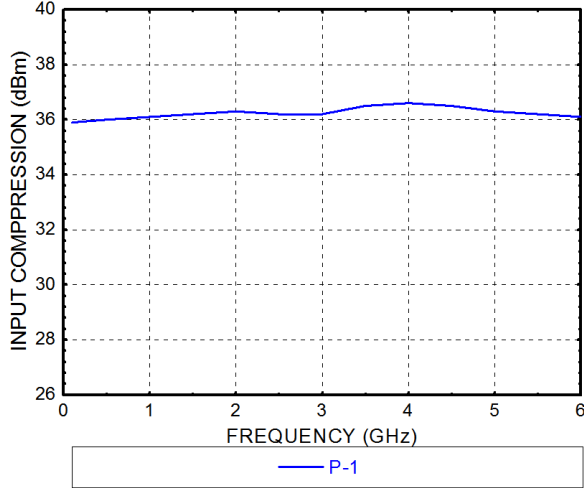


回波损耗

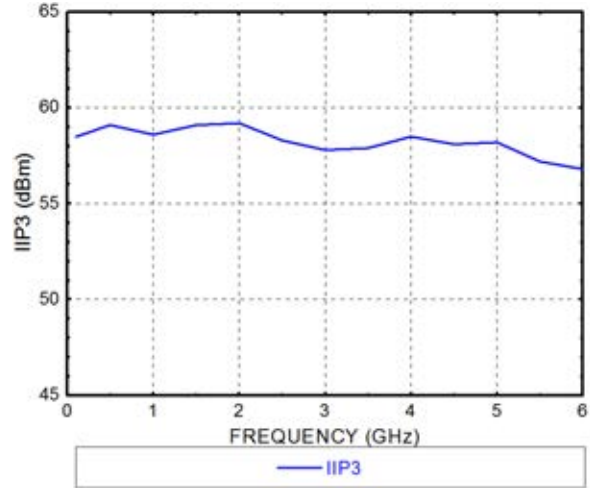




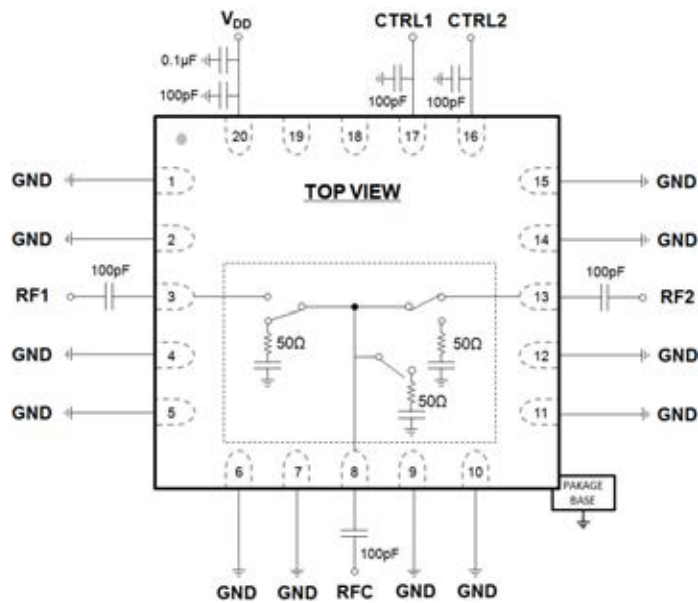
输入P₋₁



IIP3



应用框图

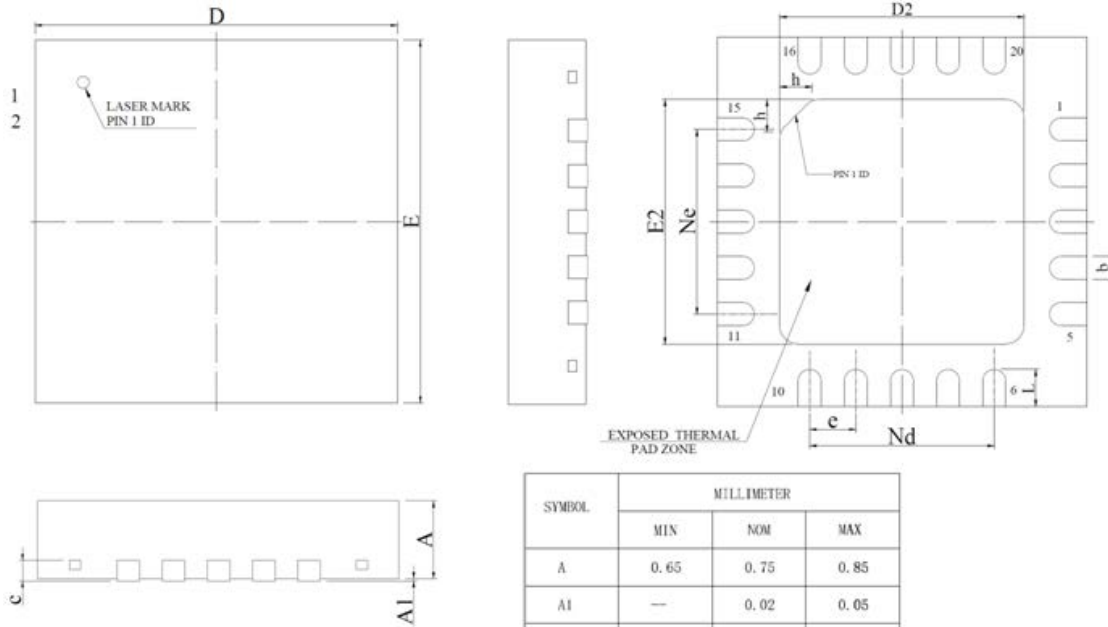


控制关系

V _{CTRL1}	V _{CTRL2}	RFC~RF1	RFC~RF2
0	0	OFF	OFF
0	1	OFF	ON
1	0	ON	OFF
1	1	OFF	OFF



物理参数



极限参数

参数	备注	数值	单位
工作电压	V_{DD}	-0.3~+5.5	V
控制电压	V_{CTL} , EN	-0.5~ $V_{DD}+0.5$	V
射频输入功率	直通	36	dBm
	负载	30	dBm
存储温度	-	-65~150	°C
热阻	直通	110	°C/W
	负载	100	°C/W
ESD	HBM	2000	V